

# MP2723 3A, I<sup>2</sup>C-Controlled SW Charger with NVDC Power Path and USB OTG

# DESCRIPTION

The MP2723 is a 3A, highly integrated, switchmode battery charge management device for single-cell Li-ion or Li-polymer batteries. This device works with NVDC system power path management, and is suitable for a variety of applications including smartphones, tablets, wireless cameras, and other portable devices. Its low-impedance power path optimizes efficiency, reduces battery charging time, and extends battery life. The I<sup>2</sup>C serial interface allows the device to be flexibly controlled due to its charging and system settings.

The MP2723 supports 5V input sources, including standard USB host ports, USB charging ports, and USB-compliant wall adapters. The device provides USB input type detection via the DP/DM pins.

It supports USB On-The-Go (OTG) operation by supplying 5V on the input bus with an output current limit up to 1.5A.

The MP2723 also initiates and completes a charging cycle without software control. It automatically detects battery voltage and charges the battery in different stages. The charger automatically terminates when it detects that the battery is fully charged. If the battery drops below its recharge threshold, the charger automatically starts another charging cycle.

The charger provides various safety features for battery charging and system operations, including a charging safety timer, battery temperature monitoring, and over-voltage and over-current protections. When any fault occurs, the charger asserts INT to host. The device provides BATFET disable control to enter shipping mode, as well as system reset functionality via the DISC pin.

The MP2723 is available in a QFN-26 (3.5mmx3.5mm) package.

## FEATURES

- 3.7V to 5.5V Operating Input Voltage Range
- Up to 22V Sustainable Voltage

- High-Efficiency, 3A, 1.35MHz Buck Charger
  - Up to 92% Charge Efficiency at 3A Charge Current
  - Auto-Detection for USB SDP, CDP, DCP, and Non-Standard Adapters
- USB OTG with 4.8V to 5.5V Adjustable Output: Up to 1.5A Output with Up to 93% Efficiency
- NVDC Power Path Management
  - Instant On Works with No Battery or Deeply Discharged Battery
  - Ideal Diode Operation in Battery Supplement Mode
- High Battery Discharge Efficiency with 14mΩ BATFET Up to 9A
- I<sup>2</sup>C Port for Flexible System Parameter Setting and Status Reporting
- Fully Integrated Power MOSFETs and Current Sensing
- Dedicated DISC Pin to Control Ship Mode and System Reset
- 13µA Low Battery Leakage Current in Shipping Mode
- Integrated ADC for Monitoring Input Voltage, Input Current, Battery Voltage, Charge Current, System Voltage, and Battery Temperature
- Charging Status Indicator
- Safety Features Include Configurable JEITA for Battery Temperature Protection for Charge Mode, Battery Charging Safety Timer, Thermal Regulation and Thermal Shutdown, Watchdog Monitoring I<sup>2</sup>C Operation, and Input/System Over-Voltage Protection

## APPLICATIONS

- Tablet PCs
- Smartphones
- Wireless Cameras
- Other Portable Devices

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# **TYPICAL APPLICATION**





## **ORDERING INFORMATION**

Part Number*	Package	Top Marking	MSL Rating	
MP2723GQC-xxxx**	QFN-26 (3.5mmx3.5mm)	See Below	1	

\* For Tape & Reel, add suffix –Z (e.g. MP2723GQC–xxxx–Z).

\*\*"xxxx" is the register setting option. The factory default is "0000." This content can be viewed in the I<sup>2</sup>C register map. Contact an MPS FAE to obtain an "xxxx" value.

## **TOP MARKING**

BNUYW

BNU: Product code of MP2723GQC Y: Year code W: Week code LLLLL: Lot number



## PACKAGE REFERENCE



## **PIN FUNCTIONS**

Pin #	Name	Туре	Description
26	DP	I/O	Positive pin of the USB data line pair.
2	IN	Ρ	<b>Power input of the IC.</b> Place a $1\mu F$ ceramic capacitor from IN to PGND, as close as possible to the IC.
3	PMID	Ρ	<b>Internal power pin.</b> Connect PMID to the drain of the reverse-blocking MOSFET and the drain of the high-side MOSFET. Bypass PMID with a 10 $\mu$ F capacitor from PMID to PGND, as close as possible to the IC.
4	SW	Р	Switching node.
5, 6, 7	PGND	Р	Power ground.
8	BST	Р	<b>Bootstrap pin</b> . Connect a 47nF bootstrap capacitor between the BST and SW pins to form a floating supply across the power switch driver to drive the power switch's gate above the supply voltage.
9	STAT	0	Open-drain charge status output to indicate various charger operations. Connect STAT to VREF using a $10k\Omega$ resistor.
10	INT	0	<b>Open-drain interrupt output</b> . The INT pin can send charging status and fault interrupt signals to the host.
11	NTC	I	<b>Temperature-sense input</b> . Connect a negative temperature coefficient thermistor to the NTC pin. Program the hot and cold temperature window with a resistor divider from VNTC to NTC to AGND. Charging is suspended when the NTC pin is out of range.
12	VNTC	0	<b>Pull-up voltage bias.</b> The VNTC pin is the pull-voltage bias of the NTC comparator resistive divider for both the feedback and the reference.
13, 14	VREF	Ρ	<b>PWM low-side driver output.</b> Connect a $10\mu$ F ceramic capacitor from VREF to AGND, as close as possible to the IC.
15	AGND	I/O	Analog ground.
16	SYS	Ρ	System output. Connect a $22\mu F$ ceramic capacitor from SYS to PGND, as close as possible to the IC.
17	BATT	Ρ	Battery positive terminal. Connect a $22\mu$ F ceramic capacitor from BATT to PGND, as close as possible to the IC.
18	CE	I	Active low charge enable pin. Battery charging is enabled when the corresponding register is set to active, and the CE pin is low.
19, 20	SCL	1	<b>I</b> <sup>2</sup> <b>C interface clock.</b> Connect SCL to the logic rail through a 10kΩ resistor.
21	SDA	I/O	I2C interface data. Connect SDA to the logic rail through a 10kΩ resistor.
22	DISC	I	Battery disconnection control pin. The DISC pin can be used for ship mode and system resetting.
23	OTG	I	<b>Boost mode enable control pin.</b> The On-The-Go function is enabled through the I <sup>2</sup> C. During boost operation, the OTG pin can go low to suspend boost operation.
24	ILIM	I	<b>Configurable input current limit.</b> To set the maximum input current limit, connect a resistor from ILIM to ground. The actual input current limit is the lower than the setting determined by the ILIM pin or the I <sup>2</sup> C.
25	DM	I/O	Negative pin of the USB data line pair.

## ABSOLUTE MAXIMUM RATINGS (1)

IN, PMID to GND0.3V to +22V SW to GND0.3V (-2V for 20ns) to +22V BST to GNDSW to SW + 5V	/
BATT, SYS to GND0.3V to +6V	
All other pins to GND0.3V to +5V	
STAT, INT sink current	4
Junction temperature150°C	2
Lead temperature (solder)260°C Storage temperature65°C to +150°C	

## ESD Ratings

Human body model (HBM)	±2kV
Charged device model (CDM)	. ±500V

#### **Recommended Operating Conditions** <sup>(3)</sup>

V <sub>IN</sub> to GND	$3.7V$ to $5.5V$ $^{(4)}$
I <sub>IN</sub>	Up to 3.25A
I <sub>SYS</sub>	
I <sub>CHG</sub>	Ūp to 3A
V <sub>BATT</sub>	Up to 4.67V
DISCHARGE (CONTINUOUS)	Up to 8.5A
IDISCHARGE (PULSE)	Up to 9A
Operating junction temp $(T_J)$	-40°C to +125°C

## Thermal Resistance <sup>(5)</sup> $\theta_{JA}$ $\theta_{JC}$

QFN-26 (3.5mmx3.5mm)...... 48..... 11... °C/W

#### Notes:

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature, T<sub>J</sub> (MAX), the junction-toambient thermal resistance,  $\theta_{JA}$ , and the ambient temperature, T<sub>A</sub>. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P<sub>D</sub> (MAX) = (T<sub>J</sub> (MAX) - T<sub>A</sub>) /  $\theta_{JA}$ . Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- The device is not guaranteed to function outside of its operating conditions.
- 4) The inherent switching noise voltage should not exceed the absolute maximum rating on either BST or SW pins. A tight layout minimizes switching loss.
- 5) Measured on JESD51-7, 4-layer PCB.

# **ELECTRICAL CHARACTERISTICS**

Parameter	Symbol	Condition	Min	Тур	Max	Units
Step-Down Converter						
Input voltage range	VIN		3.7		5.5 <sup>(6)</sup>	V
Input suspend current	lin_sus	$V_{IN} > V_{IN\_UVLO}, V_{IN} > V_{BATT},$ suspended mode, EN_HIZ = 1		1	1.5	
Input quiescent current	I <sub>IN_Q</sub>	$eq:VIN_VIN_VIN_VIN_VIN_VIN_VIN_VIN_VIN_VIN_$		4		mA
Input under-voltage lockout threshold	Vin_uvlo	V <sub>IN</sub> falling		3	3.2	V
Input under-voltage lockout threshold hysteresis		V <sub>IN</sub> rising		200		mV
Input vs. battery voltage	V <sub>HDRM</sub>	V <sub>IN</sub> rising	230	300	370	mV
headroom	V HDRM	V <sub>IN</sub> falling	120	190	260	mV
Input over-voltage protection threshold	Vin_ovlo	V <sub>IN</sub> rising	5.8	6	6.3	V
Input over-voltage protection threshold hysteresis		V <sub>IN</sub> falling		380		mV
Internal reverse-blocking MOSFET on resistance	Ron_Q1	Measure from IN to PMID		20		mΩ
High-side MOSFET on resistance	R <sub>ON_Q2</sub>	Measure from PMID to SW		37		mΩ
Low-side MOSFET on resistance	Ron_q3	Measure from SW to PGND		37		mΩ
Switching frequency	fsw	$V_{BATT} = 3.7V, I_{CHG} = 2A, REG0A[7] = 0$	1.1	1.35	1.6	MHz
SYS Output						
Minimum system regulation voltage (I <sup>2</sup> C)	Vsys_reg_min	V <sub>SYS_MIN</sub> + V <sub>TRACK</sub> , I <sub>SYS</sub> = 0, V <sub>BATT</sub> = 3.4V, REG04[3:1] = 110, REG04[0] = 1		3.82		V
Battery track voltage	Vtrack	REG04 bit[0] = 0		100		mV
Battery track voltage	VIRACK	REG04 bit[0] = 1		150		mV
Ideal diode forward voltage in supplement mode	Vfwd	10mA discharge current		20		mV
SYS vs. BATT comparator	V <sub>SYS_GT_BATT</sub>	VSYS falling to enter ideal diode mode		-20		mV
SYS vs. BATT comparator hysteresis		VSYS rising to exit ideal diode mode		50		mV
Battery good comparator (threshold compared with Vsys_MIN)	Vbatt_gd	V <sub>BATT</sub> rising to the battery FET being turned on fully		60		mV
Battery good comparator hysteresis		VBATT falling		100		mV

Parameter	Symbol	Condition	Min	Тур	Max	Units
Battery Charger						
Battery charge voltage regulation (I <sup>2</sup> C)	VBATT_REG	Depends on the I <sup>2</sup> C setting	3.4		4.67	V
Battery charge voltage regulation accuracy	Vbatt_reg _acc	$\begin{aligned} & REG07[7:1] = 1010000, \\ & V_{BATT\_REG} = 4.2V \\ & REG07[7:1] = 1011111, \\ & V_{BATT\_REG} = 4.35V \\ & REG07[7:1] = 1100100, \\ & V_{BATT\_REG} = 4.4 \end{aligned}$	-0.5		+0.5	%
Fast charge current (I <sup>2</sup> C)	Icc	Depends on the I <sup>2</sup> C setting	320		3000	mA
		Icc[5:0] = 000100, VBATT = 3.8V	462	530	598	mA
Fast charge current accuracy	Icc_acc	Icc[5:0] = 100110, VBATT = 3.8V	1849	1950	2071	mA
		$I_{CC}[5:0] = 111111, V_{BATT} = 3.8V$	2859	3000	3151	mA
Pre-charge to fast charge threshold (I <sup>2</sup> C)	V <sub>BATT_PRE</sub>	$V_{BATT}$ rising, REG05[7] = 1	2.8	3.0	3.1	V
Pre-charge to fast charge hysteresis		VBATT falling		160		mV
Trickle charge to pre-charge threshold	V <sub>BATT_TC</sub>	V <sub>BATT</sub> rising	1.9	2.0	2.1	V
Trickle charge to pre-charge threshold hysteresis		VBATT falling		50		mV
Trickle charge current	I	V <sub>BATT</sub> = 1.8V, IPRE[0] = 1		185		٣٨
Trickle-charge current	Ітс	$V_{BATT} = 1.8V, IPRE[0] = 0$		145		mA
Pre-charge current (I <sup>2</sup> C)	I <sub>PRE</sub>	Depends on the I <sup>2</sup> C setting	150		750	mA
Pre-charge current accuracy		V <sub>BATT</sub> = 2.6V, REG06[7:4] = 0010	182	225	268	mA
Charge termination current threshold (I <sup>2</sup> C)	Iterm	Determined by the I <sup>2</sup> C setting	120		720	mA
Termination current accuracy		V <sub>BATT_REG</sub> = 4.2V, REG06[3:0] = 0110	298	360	422	mA
Charge termination deglitch time	tterm_dgl			200		ms
Auto-recharge voltage threshold below V <sub>BATT_REG</sub>	VRECH	REG07[0] = 0		110		mV
Auto-recharge deglitch time	t <sub>RECH_DGL</sub>			200		ms
BATFET on resistance	R <sub>ON_Q4</sub>	V <sub>BATT</sub> = 3.8V		14		mΩ
Battery discharge current limit	IDSCHG_LMT	V <sub>IN</sub> = 0V, V <sub>BATT</sub> = 3.8V, OTG disabled, I <sub>SYS</sub> rising	8.5			А
Battery discharge function	toisc	DISC pin pulls low lasting time to turn off the battery discharge function, REG0A[1:0] = 00		8		S
controlled by DISC pin	-2100	Battery discharge off time to turn on the battery discharge function, REG0A[3:2] = 00		0.5		

Parameter	Symbol	Condition	Min	Тур	Max	Units
Input Voltage and Input Curre	nt Regulati	on				
Input minimum voltage regulation (I <sup>2</sup> C)	Vin_min		3.7		5.2	V
Input minimum voltage regulation accuracy	VIN_MIN_ACC	REG01[3:0] = 0110, V <sub>IN_REG</sub> = 4.3V	-3		+3	%
		USB500	400	450	500	
		USB900	750	825	900	
		1A	840	920	1000	
		CDP or 1.5A	1270	1400	1500	
Input current limit	I <sub>IN_LIM</sub>	DCP	1570	1690	1800	mA
		2A	1750	1880	2000	
		2.1A	1840	1970	2100	
		2.4A	2050	2240	2400	
		3A	2640	2800	3000	
Protection						
Battery over-voltage protection threshold	Vbatt_ovp	Rising, compared to $V_{BATT_REG}$		103.5		%
Battery over-voltage protection threshold hysteresis		Compared to VBATT_REG		1.5		%
Thermal regulation	$T_{J\_REG}$	T <sub>J_REG</sub> [1:0] = 11		112		°C
Thermal shutdown threshold <sup>(6)</sup>	T <sub>J_SHDN</sub>	T <sub>J</sub> rising		150		°C
Thermal shutdown hysteresis				20		°C
NTC float threshold	Vflt	As a percentage of VNTC		95		%
NTC float threshold hysteresis		As a percentage of VNTC		3.6		%
NTC low temp rising threshold	V <sub>COLD</sub>	As a percentage of VNTC	71	72	73	%
NTC low temp rising threshold hysteresis		As a percentage of VNTC		1.3		%
NTC cool temp rising threshold	V <sub>COOL</sub>	As a percentage of VNTC	59	60	61	%
NTC cool temp rising threshold hysteresis		As a percentage of VNTC		1.3		%
NTC warm temp falling threshold	Vwarm	As a percentage of VNTC	39.3	40.3	41.3	%
NTC warm temp falling threshold hysteresis		As a percentage of VNTC		1.5		%
NTC hot temp falling threshold	Vнот	As a percentage of VNTC	35.3	36.3	37.3	%
NTC hot temp falling threshold hysteresis		As a percentage of VNTC		1.5		%

Parameter	Symbol	Condition	Min	Тур	Max	Units
VREF LDO	•					•
VREF LDO output voltage	VREF	$V_{IN} = 5V$ , $I_{VREF} = 20mA$		3.6		V
VREF LDO current limit	IREF_LMT	V <sub>VREF</sub> = 3.3V	40			mA
Battery Discharge Operati	ion	-				-
Battery operating range	VBATT		2.6		4.75	V
Battery current in shipping mode	IBATT_SP	$V_{IN} < V_{IN\_UVLO}, V_{BATT} = 4.2V,$ BATFET off		13	16	μA
Battery quiescent current		$V_{IN} < V_{IN\_UVLO}$ , $V_{BATT} = 4.2V$ , BATFET on, OTG is disabled		40	47	μΑ
Battery quiescent current	BATT_Q	V <sub>IN</sub> < V <sub>IN_UVLO</sub> , V <sub>BATT</sub> = 4.2V, BATFET on, OTG is enabled		5.0		mA
OTG output voltage	V <sub>IN_DSCHG</sub>	REG03[5:3] = 011, I <sub>OTG</sub> = 0A		5.07		V
OTG output voltage accuracy		As percentage of V <sub>IN_OTG</sub> , I <sub>OTG</sub> = 0A	-2		+2	%
Battery operation UVLO	Vbatt_uvlo	V <sub>BATT</sub> falling	2.35	2.45	2.55	V
Ballery operation over		V <sub>BATT</sub> rising	2.68	2.8	2.92	V
Battery operation UVLO		V <sub>BATT</sub> falling	2.45	2.55	2.65	V
for OTG	VBATT_UVLO_OTG	V <sub>BATT</sub> rising		3.0		V
OTG output voltage protection threshold	VINOVP_DSCHG	$V_{BATT}$ = 3.7V, OTG is enabled, force a voltage at IN pin until switching is off		6.15		V
OTG output voltage protection threshold hysteresis				330		mV
OTG output current limit	IIN_DSCHG	REG03[2:0] = 000, V <sub>BATT</sub> = 3.7V	0.5	0.6	0.7	
(I <sup>2</sup> C)		REG03[2:0] = 011, V <sub>BATT</sub> = 3.7V	1.5	1.65	1.8	A
Analog-to-Digital Convert	er (ADC)					
Resolution	RES			8		bits
Input voltage range	VIN	Charge mode or OTG mode	3.6		7.62	V
Input voltage LSB	V <sub>IN_RES</sub>			60		mV
Input voltage accuracy	VIN_ACC	Charge mode or OTG mode, $V_{IN} = 5V$		2		LSB
Battery voltage range	VBATT	Charge mode or OTG mode	0		5.1	V

Parameter	Symbol	Condition	Min	Тур	Max	Units
Battery voltage LSB	VBATT_RES			20		mV
Battery voltage	Volte 100	Charge mode or OTG mode,		2		LSB
accuracy	VBATT_ACC	VBATT = 3.8V		2		LOD
Charge current LSB	I <sub>CHG_RES</sub>			17.5		mA
Charge current	ICHG_ACC	Charge mode, I <sub>CHG</sub> = 1.92A		3		LSB
accuracy				5		LOD
System voltage	Vsys	Charge mode or OTG mode	0		5.1	V
range			•		••••	
System voltage LSB	Vsys_res			20		mV
System voltage accuracy	Vsys_acc	Charge mode or OTG mode, $V_{SYS} = 3.8V$		2		LSB
Input current range	l <sub>in</sub>	Charge mode	0		3.39	А
Input current LSB	IIN_RES			13.3		mA
Input current		Charge mode, I <sub>IN</sub> = 500mA		4		LSB
accuracy		-		-		
NTC voltage range	VNTC	Charge mode or OTG mode	0		100	%
NTC voltage LSB	VNTC_RES			0.392		%
NTC voltage	VNTC_ACC	Charge mode or OTG mode, $V_{NTC} = 50\%$		2		LSB
accuracy						
DP/DM USB Detectio	n		1	1	1	
DP DCD current	DP_SRC		7	10	14	μA
source	121 _0110		-			let i
DM pull-down	Rdm_down		14.3	20	24.8	kΩ
resistance			0.05	0.005	0.4	N/
Data detect voltage	$V_{DAT\_REF}$		0.25	0.325	0.4	V
DP/DM comparator threshold (2.9V)	Vтн_2р9		2.8	2.9	3.0	V
DP/DM comparator						
threshold (2.4V)	Vth_2p4		2.3	2.4	2.5	V
DP/DM comparator						
threshold (2.2V)	Vth_2p2		2.1	2.2	2.3	V
DP/DM comparator						
threshold (1.7V)	Vth_1v7		1.6	1.7	1.8	V
DP voltage source	$V_{DP\_SRC}$		0.5	0.6	0.7	V
DM voltage source	Vdm_src		0.5	0.6	0.7	V
DP sink current	DP_SINK		70	100	130	μA
DM sink current	DM_SINK		70	100	130	μA
Leakage current			-1		+1	μΑ
		4	-1		+1	μA

#### $V_{IN} = 5V$ , $T_A = 25^{\circ}C$ , unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units			
Logic I/O Pin Characteristics (STAT, INT, OTG, /CE, DISC)									
Low logic voltage threshold	VIL				0.4	V			
High logic voltage threshold	VIH		1.3			V			
I <sup>2</sup> C Interface (SDA, SCL)									
Input high threshold level	VIH	$V_{PULL UP} = 1.8V$ , SDA and SCL	1.3			V			
Input low threshold level	VIL	$V_{PULL_{UP}} = 1.8V$ , SDA and SCL			0.4	V			
Output low threshold level	Vol	Isink = 5mA			0.4	V			
I <sup>2</sup> C clock frequency	fsc∟				400	kHz			
<b>Clock Frequency and Watchc</b>	log Timer								
Clock frequency	f <sub>CLK</sub>			5		MHz			
Watchdog timer	twdt	REG08 [5:4] = 11		160		S			

#### Notes:

6) Guaranteed by design.

# **TYPICAL PERFORMANCE CHARACTERISTICS**

 $V_{IN} = 5.0V$ ,  $V_{BATT} = full range$ ,  $I^2C$ -controlled,  $I_{CHG} = 1.92A$ ,  $I_{IN\_LIM} = 3.0A$ ,  $V_{IN\_MIN} = 4.3V$ ,  $L = 1.0\mu$ H (DCR = 14.9m $\Omega$ ),  $T_A = 25^{\circ}C$ , unless otherwise noted.



 $V_{IN} = 5.0V$ ,  $V_{BATT} = full range$ ,  $I^2C$ -controlled,  $I_{CHG} = 1.92A$ ,  $I_{IN\_LIM} = 3.0A$ ,  $V_{IN\_MIN} = 4.3V$ ,  $L = 1.0\mu$ H (DCR = 14.9m $\Omega$ ),  $T_A = 25^{\circ}$ C, unless otherwise noted.



#### Auto-Recharge



## Trickle Charge

 $V_{IN} = 5V, V_{BATT} = 1.0V, I_{TC} = 145mA$ 



Ch2: V<sub>BATT</sub> 1V/div.



#### Pre-Charge VIN = 5V, VBATT = 2.5V, IPRE = 680mA



# Constant Current Charge $V_{IN} = 5V, V_{BATT} = 3.8V, I_{CC} = 1840mA$



 $V_{IN} = 5.0V$ ,  $V_{BATT} = full range$ ,  $l^2C$ -controlled,  $I_{CHG} = 1.92A$ ,  $I_{IN\_LIM} = 3.0A$ ,  $V_{IN\_MIN} = 4.3V$ ,  $L = 1.0\mu$ H (DCR = 14.9m $\Omega$ ),  $T_A = 25^{\circ}$ C, unless otherwise noted.



Input Current Limit





**Constant Voltage Charge** 



Input Voltage Limit



#### **Power-On/Off Waveform** $V_{IN} = 5V$ , $V_{BATT} = 3.3$ , $I_{SYS} = 0.5A$ , default mode



 $V_{IN} = 5.0V$ ,  $V_{BATT} = full range$ ,  $I^2C$ -controlled,  $I_{CHG} = 1.92A$ ,  $I_{IN\_LIM} = 3.0A$ ,  $V_{IN\_MIN} = 4.3V$ ,  $L = 1.0\mu$ H (DCR = 14.9m $\Omega$ ),  $T_A = 25^{\circ}$ C, unless otherwise noted.





#### BATTFET On/Off

 $V_{IN} = 5V$ ,  $V_{BATT} = 4.0V$ ,  $I_{SYS} = 4A$ 



SYS Load Transient  $V_{IN} = 5V, V_{BATT} = 3.8V, I_{SYS} = 1A \text{ to } 4.5A, transient$ 



VIN Hot Insertion/Removal

 $V_{\text{IN}}$  = 5V,  $V_{\text{BATT}}$  = 3.3V,  $I_{\text{SYS}}$  = 4.5A, default mode



# VIN OVP Test $V_{IN} = 5V$ to 6.5V transient, $V_{BATT} = 3.3V$ , $I_{SYS} = 1A$



 $V_{IN} = 5.0V$ ,  $V_{BATT} = full range$ ,  $l^2C$ -controlled,  $I_{CHG} = 1.92A$ ,  $I_{IN LIM} = 3.0A$ ,  $V_{IN MIN} = 4.3V$ ,  $L = 1.0 \mu H$  (DCR = 14.9m $\Omega$ ), T<sub>A</sub> = 25°C, unless otherwise noted.



**OTG Mode Start-Up** 

**Battery Discharge Current** 



## **OTG Steady State Operation**





 $V_{IN}$  = float, OTG mode,  $V_{BATT}$  = 4.0V, IIN\_DSCHG = 1.5A, IOTG = 1.5A



**NTC JIETA Operation**  $V_{IN} = 5V, V_{BATT} = 4.1V, I_{SYS} = 0A,$ 





# FUNCTIONAL BLOCK DIAGRAM







# **OPERATION**

The MP2723 is a highly integrated, 3A, switchmode battery charger IC with NVDC power path management for single-cell Li-ion or Li-polymer battery applications. The device integrates a reverse blocking FET (Q1), high-side switching FET (Q2), low-side switching FET (Q3), and battery FET (Q4) between the SYS and BATT pins.

#### **Power Supply**

The VREF pin's voltage supplies the internal bias circuits as well as the high-side and low-side MOSFET gate drive. The pull-up rail of STAT can also be connected to VREF. The VREF pin has an internal LDO, which has two inputs. One input is from IN, and the other is from a battery. VIN and the battery voltage are connected to the input of the LDO via a PMOS.

Figure 2 shows the VREF power supply circuit.



Figure 2: VREF Power Supply Circuit

#### **Device Power-Up from an Input Source**

When an input source is plugged in, the MP2723 qualifies the input source before start-up. The input source must meet the following requirements:

- 1.  $V_{IN} > V_{BATT} + V_{HDRM}$
- 2.  $V_{IN\_UVLO} < V_{IN} < V_{IN\_OVLO}$

If the input power source meets the conditions above, a good input is detected, and the device asserts an INT to host. Then the device detects the input source type via the DP/DM pins. When DP/DM detection completes, the status register bit (VIN\_STAT) changes, and an INT pulse is sent to the host. Then the device starts up the step-down converter.

## **NVDC Power Path Management**

The MP2723 employs a narrow-voltage DC (NVDC) power structure with the battery FET, decoupling the system from the battery and thus allowing separate controls between the system and the battery. The system is a priority during

start-up, even if the battery is deeply discharged or missing. If the input power is available with a depleted battery, the system voltage is regulated at the minimum system voltage (V<sub>SYS\_REG\_MIN</sub>).

Figure 3 shows the NVDC power structure, which is composed of a front-end, step-down DC/DC converter, and a battery FET placed the between SYS and BATT pins.



Figure 3: NVDC Power Path Management Structure

The DC/DC converter is a 1.35MHz step-down switching regulator, which drives the system load directly, and charges the battery through the battery FET.

The system regulates the voltage in the following ways:

- If the battery voltage drops below V<sub>SYS\_MIN</sub>, the system voltage is regulated at a minimum system voltage (V<sub>SYS\_REG\_MIN</sub>), which exceeds V<sub>SYS\_MIN</sub> by V<sub>TRACK</sub>. The battery FET works linearly to charge the battery via trickle charge, pre-charge, or fast charge current, depending on the battery voltage. V<sub>SYS\_MIN</sub> can be set via register REG04 bit[3:1], and V<sub>TRACK</sub> can be set via REG04 bit[0].
- 2. When the battery voltage exceeds  $V_{SYS\_MIN} + V_{BATT\_GD}$  (60mV), the battery FET fully turns on, and the voltage difference between the system and the battery is the  $V_{DS}$  of BATFET. The charge current loop is implemented by the PWM control of the DC/DC converter.
- If charging is suspended or completed (the battery FET is off), the system voltage is always regulated at its maximum value, (V<sub>SYS\_MIN</sub>, V<sub>BATT</sub>) + V<sub>TRACK</sub>.

Figure 4 shows how the voltage is regulated.



b) Charging Disabled

Figure 4: V<sub>SYS</sub> Variation with VBATT

## **Dynamic Power Management**

To meet the maximum current limit in USB specifications and avoid overloading the adapter, the MP2723 features dynamic power management (DPM), and continuously monitors the input current and input voltage. The total input current limit is configurable to prevent the input source from being overloaded. If the input current increases and reaches the input current limit, the charge current is reduced to prioritize the system power.

If the preset input current limit exceeds the adapter's rating, the additional minimum input voltage regulation loop activates to prevent the input power source from being overloaded. When the input voltage falls below the input voltage regulation threshold due to a heavy load, the charge current is reduced to prevent the input voltage from dropping further.

Power path management can operate in two ways:

 If V<sub>BATT</sub> < V<sub>SYS\_MIN</sub> + V<sub>BATT\_GD</sub>, the system voltage is regulated at V<sub>SYS\_REG\_MIN</sub>. If the input current or voltage regulation threshold is reached, the input current loop or input voltage loop controls the DC/DC converter, the system voltage drops, and the battery FET driver is pulled down to decrease the charge current. This prioritizes the system power requirement.

2. This case occurs if the battery is directly connected to the system, and  $V_{BATT} > V_{SYS\_MIN}$  +  $V_{BATT\_GD}$ . Due to the free transition between each control loop, the charge decreases automatically when the input current limit or voltage regulation threshold is reached.

## **Battery Supplement Mode**

If the device reaches the input current limit or input voltage threshold, the charge current decreases. If the input source is still overloaded when the charge current decreases to zero, the system voltage starts to collapse. If the system voltage drops below the battery voltage, the MP2723 enters battery supplement mode, in which the battery simultaneously powers the system and the DC/DC converter.

The MP2723 offers ideal diode mode to optimize the control transition between the battery FET and the DC/DC converter. The battery FET enters ideal diode mode under either of the following conditions:

- a)  $V_{IN}$  start-up from the battery supply system
- b)  $V_{BATT} < V_{SYS\_MIN}$ , and the system voltage drops below the battery voltage

During ideal diode mode, the battery FET operates as an ideal diode, and regulates the gate drive of battery FET. The  $V_{DS}$  of the battery FET stays at about 20mV. As the discharge current increases, the battery FET's gate drive increases and its  $R_{DS}$  decreases until the battery FET is fully on.

## **Battery Charge Profile**

If  $V_{IN}$  powers on, CHG\_CONFIG bit = 01, and the

CE pin is low, the device completes a charging cycle without host involvement. However, the host can set different charging parameters to optimize the charge profile by writing to the corresponding registers via the l<sup>2</sup>C.

A new charge cycle starts when all of the following conditions are valid:

• Good input power is inserted

- Battery charging is enabled by the I<sup>2</sup>C, and CE is forced to a low logic
- There is no thermistor fault on the NTC pin
- There is no safety timer fault
- BATFET is not forced to turn off

The MP2723 provides four main charging phases: trickle charge, pre-charge, constant current charge, and constant voltage charge, described below:

<u>Phase 1 (trickle charge)</u>: When the input power qualifies as a good power supply, the MP2723 checks the battery voltage to decide if trickle charge is required. If the battery voltage is below  $V_{BATT_TC}$  (2.0V), a trickle-charge current is applied on the battery, which helps reset the protection circuit in the battery pack. The trickle-charge current can be set via REG06 bit[4]. If REG06 bit[4] is set to 1, the trickle-charge current is 185mA. If REG06 bit[4] is set to 0, the trickle-charge current is 145mA.

<u>Phase 2 (pre-charge)</u>: If the battery voltage exceeds  $V_{BATT_TC}$ , the MP2723 starts to safely precharge the depleted battery until the battery voltage reaches the pre-charge to fast charge threshold ( $V_{BATT_PRE}$ ). If  $V_{BATT_PRE}$  is not reached before the pre-charge timer (1hr) expires, the charge cycle ends and a corresponding timeout fault signal is asserted. The pre-charge current can be configured via I<sup>2</sup>C register REG06 bit [7:4], and can be set between 150mA and 750mA.

<u>Phase 3 (constant current charge)</u>: If the battery voltage exceeds  $V_{BATT_PRE}$  (set via REG05 bit[7]), the MP2723 enters a constant current charge (fast charge) phase. The fast-charge current can be configured to as high as to 3A via REG05 bit[5:0].

There are two stages during fast charge. First, the battery FET works linearly to charge the battery with fast charge current. Once the battery voltage exceeds  $V_{SYS\_MIN} + V_{BATT\_GD}$ , the battery FET is fully turned on. The charge current loop is implemented by the PWM control of the buck converter.

<u>Phase 4 (constant voltage charge)</u>: When the battery voltage rises to the configurable float voltage ( $V_{BATT_REG}$ ) set via REG07 bit[7:1], the charge current begins to taper off.

The charge cycle is considered complete when the charge current reaches the battery termination threshold ( $I_{TERM}$ ) set via REG06 bit[3:0] after a 200ms termination deglitch time, assuming the termination function is enabled if REG08 bit[7] is set to 1. If  $I_{TERM}$  is not reached before the safety charge timer expires (see the Safety Timer section on page 24), the charge cycle ends, and a corresponding timeout fault signal is asserted.

Figure 5 shows the charge profile.





During the charging process, the actual charge current may be less than the register setting due to other loop regulations, like dynamic power management (DPM) regulation (input current limit or input voltage regulation loop), or thermal regulation. The thermal regulation reduces the charge current so that the IC junction temperature does not exceed the preset limit. The multiple thermal regulation thresholds from 60°C to 120°C help the system design meet the thermal requirements in different applications. The junction temperature regulation threshold can be set via REG02 bit[3:2].

#### **Automatic Recharge**

When the battery is done charging, the battery may be discharged due to system consumption or self-discharge. When the battery voltage is discharged below the recharge threshold after a 200ms auto-recharge deglitch time, the MP2723 automatically starts a new charging cycle.

#### **CE Control**

CE is a logic input pin that enables or disables for battery charging, or restarts a new charging cycle. Battery charging is enabled when CHG\_CONFIG

(REG04 bit[5:4]) is set to 01 and the CE pin is pulled to logic low.

#### **Battery Over-Voltage Protection (OVP)**

The MP2723 is designed with built-in battery overvoltage protection (OVP). When the battery voltage exceeds 103.5% of  $V_{BATT\_REG}$ , the MP2723 immediately suspends the charging and asserts a fault. When battery OVP occurs, only the charging is disabled, and the DC/DC converter keeps operating.

#### System Over-Voltage Protection (OVP)

The MP2723 monitors the voltage at the SYS pin. When an over-voltage condition ( $V_{SYS} > V_{BATT_REG} + 0.4V$ ) is detected, the DC/DC converter turns off and the system is powered by the battery via the BATFET.

#### Automatic Input Current Optimizer

The device provides an optimized input current limit without overloading the input source. This function can be enabled or disabled by configuring the AICO\_EN bit, which is disabled by default. If AICO is enabled,  $I_{IN\_LIM}$  is set to a larger current, and the input voltage drops to  $V_{IN\_MIN}$ , the AICO function is triggered. This function decreases

 $I_{IN\_LIM}$  step by step, until the input voltage exits  $V_{IN\_MIN}$  control. The input current limit remains optimized and does not automatically run the AICO function unless another  $V_{IN\_MIN}$  event occurs.

The actual input current limit is reported in the  $I_{IN\_DPM}$  register when the AICO function is enabled (AICO\_EN = 1). If the AICO function is disabled (AICO\_EN = 0), the input current limit is set by the  $I_{IN\_LIM}$  register. Any write to  $I_{IN\_LIM}$  can reset  $I_{IN\_DPM}$  to the same value of  $I_{IN\_LIM}$  when the AICO function is enabled.

#### **Input Source Type Detection**

The MP2723 features input source detection that is compatible with USB Battery Charging Specification 1.2 (BC1.2) and nonstandard adapters. The user can force DP/DM detection in the host mode by writing 1 to the USB\_DET\_EN bit (REG0B bit[5]).

When the input voltage is first applied, and good input source is detected, the BC1.2 detection starts first with data content detection (DCD). If DCD is effective, the standard downstream port (SDP), charging downstream port (CDP), and dedicated charging port (DCP) can be distinguished. If the 500ms DCD timer expires, then the MP2723 proceeds with nonstandard adapter detection.

DCD uses a current source to detect when the data pins have made contact during an attach event. The protocol for DCD is as follows:

- The portable device (PD) detects V<sub>IN</sub> assertion
- The PD turns on DP I<sub>DP\_SRC</sub> and the DM pulldown resistor
- The PD waits for the DP line to be low
- If the DP line is detected to be low for 10ms, the PD starts primary detection
- If data contact is not detected, the DCD timer (500ms) expires

After the DCD timer expires, the PD turns off  $I_{DP\_SRC}$  and the DM pull-down resistor. Then the 50ms timer starts, and the PD can detect a special adapter. If a special adapter is detected, an INT is sent to host. Otherwise, the PD starts primary detection after the 50ms timer expires.



Primary detection is used to distinguish between USB hosts (or the SDP) and different types of charging ports. During primary detection, the IC turns on  $V_{DP\_SRC}$  on DP, and  $I_{DM\_SINK}$  on DM. If the portable device is attached to a USB host, the DM pin pulls low. The SDP is detected, and sends an INT signal to the host.

If the DM pin is high, the IC goes into secondary detection, which distinguishes between a CDP and a DCP.

During secondary detection, the IC turns on  $V_{DM\_SRC}$  on DM, and  $I_{DP\_SINK}$  on DP. If the input source is a CDP port and DP is low, then the CDP is detected and an INT signal is sent to the host. If DP is high, the DCP source is detected, and an INT is sent to host.

Table 1 lists input current limits that are compatible with the USB specifications and BC1.2.

DP/DM Detection	I <sub>IN_LIM</sub> (A)	V <sub>IN_OVP</sub> (V)	V <sub>IN_MIN</sub> (V)
Nonstandard adapter (1A)	1	6	3.7 to 5.2
Nonstandard adapter (2.1A)	2.1	6	3.7 to 5.2
Nonstandard adapter (2.4A)	2.4	6	3.7 to 5.2
SDP	0.5	6	3.7 to 5.2
CDP	1.5	6	3.7 to 5.2
DCP	1.8	6	3.7 to 5.2

Table 1: Input Current Limit vs. USB Type

USB detection is independent of the charge enable status. After DP/DM detection completes, the MP2723 indicates the USB port type in status register VIN\_STAT (REGOC bit[7:5]), and asserts an INT signal to the host. The host can revise the input current limit according to VIN\_STAT.

#### Input Current Limit Setting via ILIM

For safe operation, the MP2723 has an additional hardware pin (ILIM) to adjust the maximum input current limit. The limit can be set by connecting a resistor from ILIM to GND. The actual input current limit is the lower value between what is set by the ILIM pin and the value set by the I<sup>2</sup>C.

The current limit set by the ILIM pin can be calculated with Equation (1):

$$I_{\text{IN\_LIM}} = \frac{120}{R_{\text{ILIM}}(k\Omega)}(A)$$
(1)

# Battery Temperature Monitoring in Charge Mode

The MP2723 continuously monitors the battery's temperature by measuring the voltage at the NTC pin. This value is typically determined by a negative temperature coefficient (NTC) thermistor and external voltage dividers. For the NTC thermistor, a hotter ambient temperature corresponds with a lower resistance and voltage ratio, and vice versa.

Figure 6 shows an NTC protection circuit. The external resistor dividers and the internal reference resistor series are pulled up to the VNTC pin. The voltage ratios between the internal and external dividers are compared to determine if an NTC protection has been triggered. The VNTC voltage (1.7V) is regulated by an LDO that is powered from VREF. The VNTC pin is available in both charge mode and OTG mode.



Figure 6: NTC Protection Circuit

The MP2723 provides standard and JEITA battery temperature monitoring, which can be selected by the NTC\_TYPE bit. If the standard type is selected, and the external voltage ratio transitions from the high temperature threshold ( $V_{HOT}$ ) to the low temperature threshold ( $V_{COLD}$ ), this means that the battery temperature is out of the cold-to-hot range. The IC suspends charging and reports the NTC fault. Charging resumes automatically after the battery temperature is within the cold-to-hot temperature range again.

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If the JEITA type is selected, the MP2723 monitors four temperature thresholds: the cold temperature threshold ( $T_{NTC}$  < 0°C, default), the cool temperature threshold (0°C <  $T_{NTC}$  < 15°C, default), the warm temperature threshold (45°C <  $T_{NTC}$  < 55°C, default), and the hot temperature threshold ( $T_{NTC}$  > 55°C, default).

For a given NTC thermistor, these temperatures correspond to the values for  $V_{COLD}$ ,  $V_{COOL}$ ,  $V_{WARM}$ , and  $V_{HOT}$ . These voltage thresholds can be configured via REG16 bit[5:0] to set different temperature ranges.

If  $V_{NTC} < V_{HOT}$  or  $V_{NTC} > V_{COLD}$ , the charging and timers are suspended. If  $V_{HOT} < V_{NTC} < V_{WARM}$ , the battery regulation voltage ( $V_{BATT_REG}$ ) is reduced by 200mV, which can be configured via REG16 bit[7]. If  $V_{COOL} < V_{NTC} < V_{COLD}$ , the charging current is reduced to 16.7%, which can be configured via REG16 bit[6]. Figure 7 shows JEITA control.



Figure 7: NTC Window

The MP2723 provides PCB over-temperature monitoring. The PCB over-temperature response is selected by the NTC OPT bit (REG02 bit[1]). If this bit is set to 1, PCB over-temperature protection is enabled. If this bit is set to 0 (the default setting), the battery temperature monitoring and corresponding protection features mentioned above are utilized instead.

While monitoring over-temperature condition in the PCB, the IC continuously monitors the PCB temperature at the NTC pin. If the NTC pin voltage is below the threshold that reuses  $V_{HOT}$ , the DC/DC converter and battery FET turn off. Operation resumes once the NTC pin voltage goes back to the normal value.

If the NTC thermistor is removed, NTC is pulled up to VNTC (see Figure 6). If the MP2723 detects an

NTC voltage exceeding 95% of VNTC, then the NTC thermistor float is detected. The MP2723 sends an INT signal to the host, and the RNTC FLOAT\_STAT bit is set to 1.

# Battery Temperature Monitoring in OTG Boost Mode

In boost mode, the device monitors the battery temperature to be between the  $V_{COLD}$  and  $V_{HOT}$  thresholds unless the boost mode temperature is disabled by setting EN\_OTG NTC (REG02 bit[5]) to 0. When the temperature is outside the temperature thresholds, boost mode is suspended. Once the temperature is within the thresholds, boost mode resumes.

#### **Charging STAT Indication**

The MP2723 indicates the charging state on the open drain of the STAT pin (see Table 2). The STAT pin be disabled by setting the STAT\_EN bit to 0.

Charging State	STAT
In charging	Low
Charging done, charging disabled, input OVP, battery discharge mode	High
Charging suspended (battery OVP, system OVP, timer fault, NTC fault, NTC float)	Blinking at 1Hz

## Interrupt to Host (INT)

The MP2723 has an alert mechanism that can output an interrupt signal via the INT pin to notify the system of the operation by outputting a 256µs low-state INT pulse. The events that can trigger an INT output are listed below:

- Good input source detected
- DP/DM USB detection completed
- Input removed
- Charge completed
- NTC float is detected
- VINPPM or IINPPM is reached
- Any fault in REG0D (watchdog timer fault, OTG fault, thermal shutdown, safety timer fault, battery OVP fault, NTC fault)

If a fault occurs, the charger device sends out INT signal. The fault is not latched, and always reports the current conditions.



#### Safety Timer

The MP2723 provides both a pre-charge and a complete charge safety timer to prevent extended charging cycles due to abnormal battery conditions. The total safety timer for both trickle charge and pre-charge is 1 hour when the battery voltage is below  $V_{BATT_PRE}$ . The complete charge safety timer starts when the battery enters constant current charge. The user can configure the constant current charge safety timer via the CHG\_TMR bit (REG08 bit[2:1]) through the l<sup>2</sup>C. If the safety timer function is not used, it can be disabled by EN\_TIMER (REG08 bit[0]) via the l<sup>2</sup>C during initializing charger configuration.

The safety timer is reset at the beginning of a new charging cycle. Before safety timer expires, any of the actions listed below can reset the safety timer:

- A new charge cycle begins by either input insertion or automatic recharge
- Toggle the CE pin low to high to low (charge enable)
- Write CHG\_CONFIG (REG04 bits[5:4]) from 00 to 01 (charge enable)
- Write EN\_TIMER (REG08 bit[0]) from 0 to 1 (safety timer enable)

When safety timer expires, the safety timer fault bit (REG17 bit[7]) is set to 1 and an INT is asserted to the host. Writing BG\_EN bit (REG09 bit[3]) from 1 to 0 or re-inserting input will reenable the input detection, clear safety timer fault and restart the safety timer.

The MP2723 automatically adjust or suspend the timer when any fault occurs. The timer is suspended under any condition listed below:

- Battery enters supplement mode and V<sub>BATT</sub> < V<sub>SYS\_MIN</sub>
- Battery OVP occurs
- NTC hot or cold fault
- NTC float
- Write EN\_TIMER (REG08 bit[0]) from 1 to 0 (termination is disabled)

The MP2723 provides a way to double the remaining time left on the timer, and is enabled by the TMR2X\_EN bit. If the input current limit, input voltage regulation, or thermal regulation

threshold is reached, the remaining time on the timer is doubled when TMR2X\_EN is enabled. Once the device is cleared of the above conditions, remaining time returns to the original setting.

The safety timer does not operate in USB OTG mode.

#### Watchdog Timer

The MP2723 is host-controlled device, but it can operate in default mode which is without host control. In default mode, all the registers are in the default settings, the WATCHDOG\_FAULT is 1.

In host-controlled mode, all the parameters can be programmed by the host. To keep the device in host mode, the host has to periodically reset the watchdog by setting the Watchdog Timer Reset bit (REG08 Bit[3]) to 1 before the watchdog timer expires. If the watchdog timer expires, some of the registers will reset to their default values. See the Register Map on page X to see which registers are reset after watchdog timer expires.

The following actions reset the watchdog timer and make the IC recover from a watchdog timer fault:

- Write 1 to the Watchdog Timer Reset bit (REG08 bit[3])
- Toggling the watchdog timer enable bit (disable first, then enable)

#### Thermal Regulation and Thermal Shutdown

The MP2723 continuously monitors the internal junction temperature to maximize power delivery and avoid overheating the chip. When the internal junction temperature reaches the thermal regulation threshold (which is set by the  $T_{J_REG}$  bit), the MP2723 starts to reduce the charge current to prevent higher power dissipation. During thermal regulation, the THERM\_STAT bit is set to 1.

If the junction temperature reaches the thermal shutdown threshold  $T_{J\_SHDN}$  (150°C), the MP2723 turns off the PWM step-down converter and BATFET. The THERMAL SHUTDOWN bit in the fault register is set to 1, and an INT signal is asserted to the host. The step-down converter and BATFET recover to normal operation when the junction temperature drops below the  $T_{J\_SHDN}$  hysteresis (20°C).

#### **Battery Discharge Mode**

If only the battery is connected to the device and  $V_{BATT}$  exceeds the  $V_{BATT_UVLO}$  threshold, the battery FET turns on and connects the battery to the system. The 14m $\Omega$  battery FET minimizes the conduction loss during discharge. The quiescent current of the MP2723 is as low as 40µA. The low on resistance and low quiescent current help extend the battery's runtime.

There is an over-current limit designed in the MP2723 to avoid system over-current conditions during battery discharging. If the discharge current exceeds this limit (I<sub>DSCHG\_LMT</sub>) for a 50µs blanking time, the discharge FET turns off and enters hiccup mode. After a 600ms recovery time, the discharge FET turns on again. If the discharge current goes high to reach an internal fast-off current limit (14A), the battery FET turns off immediately and initiates hiccup mode.

#### **Battery Disconnection Function**

In applications where the battery is not removable, disconnect the battery from the system for shipping mode or to reset of system's power. The MP2723 provides both shipping mode and system reset mode for different applications.

The MP2723 can enter and exit shipping mode through the I<sup>2</sup>C control of the BATFET\_DIS bit (REG0AH bit[5]). Writing 1 to BATFET\_DIS turns off BATFET after a 10s delay. In battery discharge mode, the delay time is programmed by the  $t_{SM_DLY}$  bit. Writing 0 to BATFET\_DIS turns the battery FET on again.

If an application requires the system's power to be reset, the MP2723 uses a dedicated DISC pin to cut off the path from the battery to the system.

The system has two reset functions that can be selected via the SYSRST\_SEL bit (REG0A bit[4]). If SYSRST\_SEL is set to 1, and the logic at DISC is pulled low for more than 8s (which can be configured by the  $t_{DISC\_L}$  bit (REG0A[1:0])), the system is disconnected from the battery by turning off the battery FET. After the 4s low period (which can be configured by the  $t_{DISC\_H}$  bit (REG0A bit[3:2])), BATFET automatically turns on (see Figure 8).



Figure 8: System Software Reset (SYSRST\_SEL = 1)

If the SYSRST\_SEL bit (REG0A bit[4]) is set to 0, once the logic at DISC is pulled low for more than the time programmed by the  $t_{DISC_L}$  bit, BATFET turns off. Once the logic at DISC is pulled low again for the time specified by the  $t_{DISC \ H}$  bit, BATFET turns on (see Figure 9).



(SYSRST\_SEL = 0)

#### **OTG Boost Function**

The MP2723 can supply a regulated 5V output at the IN pin to power the peripherals. This output is compliant with USB On-The-Go (OTG) specifications. The MP2723 does not enter OTG mode if the battery is below the battery undervoltage lockout (UVLO) threshold, to ensure that the battery is not drained. To enable OTG mode, the input voltage at the IN pin must be below 1.0V.

Boost operation can be enabled when the CHG\_CONFIG bit = 11 (REG04 bit[5:4] = 11), and the OTG pin is high. The OTG output current limit can be configured by the  $I_{IN_DSCHG}$  bit (REG03 bit[1:0]) via the I<sup>2</sup>C. During boost mode, the status register VIN\_STAT (REG0C bit[7:5]) changes to 111.

The following conditions must be met to enable boost operation:

- V<sub>BATT</sub> > V<sub>BATT\_UVLO\_OTG</sub> (rising 3V)
- V<sub>IN</sub> < 1V</li>

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- OTG pin is high and the CHG\_CONFIG bit (REG04 bit[5:4]) is set to 11
- Boost mode enabled after 200ms delay

Once OTG is enabled, the MP2723 boosts the PMID to 5.0V. Then the block FET (Q1) is linearly regulated with a 3A output current limit. When  $V_{IN}$  is charged above 4.4V within 6ms, the block FET fully turns on. Otherwise, the block FET turns off and the part goes into hiccup mode. After a 600ms off period, PMID tries to charge  $V_{IN}$  again.

The MP2723 provides OTG output short protection. If  $V_{IN}$  falls below 4.0V, the block FET and boost turn off, and the part enters hiccup mode. After a 600ms recovery time, OTG starts up again. When the OTG output is short, the fault register's OTG\_FAULT bit (REG0D bit[6]) is set to 1, and an INT signal is sent to the host. The device also provides OTG output voltage protection. Once  $V_{IN}$  exceeds  $V_{INOVP_DSCHG}$ , the MP2723 stops switching, the fault register OTG\_FAULT bit (REG0D bit[6]) is set to 1, and an INT signal is sent to the host.

In boost mode, the MP2723 employs a fixed 1.35MHz PWM step-up switching regulator. It switches from PWM operation to pulse-skip operation at light-load.

## ADC

The MP2723 integrates an 8-bit ADC, which is available in charge mode and OTG mode. In charge mode, the ADC monitors input voltage, input current, system voltage, battery voltage, charge current, and NTC voltage alternatively. In OTG mode, the ADC monitors battery voltage, system voltage, NTC voltage and input voltage. When ADC function is available, the ADC can be controlled by the ADC\_START bit.

ADC operation has two modes, which can be selected by ADC\_RATE. If ADC\_RATE is 0, ADC acts once when an I<sup>2</sup>C command is issued. If ADC\_RATE is 1, ADC always acts in a round-robin manner.

## **Series Interface**

The MP2723 uses an I<sup>2</sup>C-compatible interface to set the charging parameters and instantaneously report the device status. The I<sup>2</sup>C is a bidirectional, two-wire serial interface developed by Philips Semiconductor (now NXP Semiconductors). Only two bus lines are required: a serial data line (SDA) and serial clock line (SCL).

Devices are considered masters or slaves when performing data transfers. A master is the device that initiates a data transfer on the bus and generates the clock signals to permit that transfer. At that time, any device addressed is considered as a slave.

The device operates as a slave device with address 4BH, receiving control inputs form the master device like microcontroller or a digital signal processor.

The I<sup>2</sup>C interface supports both standard mode (up to 100kbits), and fast mode (up to 400kbits). Both SDA and SCL are bidirectional lines, connecting to the positive supply voltage via a current source or pull-up resistor. When the bus is free, both lines are high. The SDA and SCL pins are open-drain.

The data on the SDA line must be stable during the high period of the clock. The high or low state of the data line can only change when the clock signal on the SCL line is low. One clock pulse is generated for each data bit transferred (see Figure 10).

All transactions begin with a start command (S), and can be terminated by a stop command (P). A high-to-low transition on the SDA line while SCL is high defines a start condition. A low-tohigh transition on the SDA line when SCL is high defines a stop condition (see Figure 11).

Start and stop conditions are always generated by the master. The bus is considered busy after the start condition, and free after the stop condition.

Every byte on the SDA line must be 8 bits long. The number of bytes to be transmitted per transfer is unrestricted. Each byte has to be followed by an acknowledge (ACK) bit. Data is transferred with the most significant bit (MSB) first. If a slave cannot receive or transmit another complete byte of data until it has performed some other function, it can hold the clock line (SCL) low to force the master into a wait state, called clock stretching. Data transfer then continues when the slave is ready for another byte of data and releases the clock line (see Figure 12).



An acknowledge signal takes place after every byte. The acknowledge bit allows the receiver to signal the transmitter that the byte was successfully received and another byte may be sent. All clock pulses, including the acknowledge 9th clock pulse, are generated by the master.

The transmitter releases the SDA line during the acknowledge clock pulse so the receiver can pull the SDA line low. If it remains high during the 9th clock pulse, this is the not acknowledge (NACK) signal. The master can then generate either a stop to abort the transfer or a repeated start to begin a new transfer.

After the start, a slave address is sent, this address is 7 bits long followed by the 8th data direction bit (R/W). A 0 indicates a transmission (write), and a 1 indicates a request for data (read). Figure 13, Figure 14, Figure 15, Figure 16, and Figure 17 show the complete data transfer sequence.

If the register address is not defined, the charger IC sends back NACK and returns to an idle state.

The charger device supports multi-read and multi-write on its registers.



Figure 13: Complete Data Transfer



Figure 17: Multi-Read

# I<sup>2</sup>C REGISTER MAP

5

n P.

П

IC Address 4BH Register Name	Address	R/W	Description
REG00	0x00	R/W	Input current limit.
REG01	0x01	R/W	Input voltage regulation.
REG02	0x02	R/W	NTC configuration and thermal regulation.
REG03	0x03	R/W	ADC control and OTG configuration.
REG04	0x04	R/W	Charge control and VSYS configuration.
REG05	0x05	R/W	Charge current configuration.
REG06	0x06	R/W	Pre-charge and termination current.
REG07	0x07	R/W	Charge voltage regulation.
REG08	0x08	R/W	Timer configuration.
REG09	0x09	R/W	Bandgap.
REG0A	0x0A	R/W	BATFET configuration.
REG0B	0x0B	R/W	INT MASK and USB detection.
REG0C	0x0C	R	Status.
REG0D	0x0D	R	Fault.
REG0E	0x0E	R	ADC of battery voltage.
REG0F	0x0F	R	ADC of system voltage.
REG10	0x10	R	ADC of NTC voltage.
REG11	0x11	R	ADC of input voltage.
REG12	0x12	R	ADC of charge current.
REG13	0x13	R	ADC of input current.
REG14	0x14	R	Power management status.
REG15	0x15	R/W	DPM mask.
REG16	0x16	R/W	JEITA configuration.
REG17	0x17	R	Safety timer status and part number.

#### **REG00H: Input Current Limit**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	EN_HIZ	0	Y	Y	R/W	0: Disable 1: Enable	Hi-Z mode enable bit. Set to 0 by default. This bit only turns off the DC/DC converter.
6	EN_LIM	1	Y	Y	R/W	0: Disable 1: Enable	Enable bit for the ILIM pin. Set to 1 by default. The charger input current limit is the lower value between the IIN_LIM register setting and ILIM pin setting.
5	IIN_LIM [5]	0	Y	Ν	R/W	1600mA	-
4	I <sub>IN_LIM</sub> [4]	0	Y	Ν	R/W	800mA	This bit sets the input current limit threshold. It has a 100mA
3	I <sub>IN_LIM</sub> [3]	1	Y	Ν	R/W	400mA	offset, a 500mA default, and a 100mA to 3.25mA via the one-time programmable (OTP). $V_{IN}$ POR can reset $I_{IN\_LIM}$ to the default OTP threshold.
2	I <sub>IN_LIM</sub> [2]	0	Y	Ν	R/W	200mA	
1	I <sub>IN_LIM</sub> [1]	0	Y	Ν	R/W	100mA	
0	I <sub>IN_LIM</sub> [0]	0	Y	Ν	R/W	50mA	

#### **REG01H: Input Voltage Regulation**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	REGISTER RESET	0	Y	Ν	R/W	0: Keep current setting 1: Reset	This bit is set to 0 by default.
6	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
5	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
4	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
3	V <sub>IN_MIN</sub> [3]	0	Y	Ν	R/W	800mV	This bit sets the input voltage
2	V <sub>IN_MIN</sub> [2]	1	Y	Ν	R/W	400mV	limit threshold. It has a $3.7V$ offset, $3.7V$ to $5.2V$ range, and is set to 0110 by default. V <sub>IN</sub> POR can reset V <sub>IN_MIN</sub> to its default value via the OTP.
1	Vin_min [1]	1	Y	Ν	R/W	200mV	
0	Vin_min [0]	0	Y	Ν	R/W	100mV	

## **REG02H: NTC Configuration and Thermal Regulation**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	tsm_dly	1	Y	Y	R/W	0: No delay 1: 10s delay	This bit sets the shipping mode entry delay time. It is set to 1 by default.
6	NTC_TYPE	1	Y	Y	R/W	0: Standard 1: JEITA	This bit is set to 1 by default.
5	EN_OTG NTC	0	Y	Y	R/W	0: Disable 1: Enable	OTG NTC enable bit. This bit is set to 0 by default.
4	EN_CHG NTC	1	Y	Y	R/W	0: Disable 1: Enable	Charge NTC enable bit. This bit is set to 1 by default.
3	T <sub>J_REG</sub> [1]	1	Y	Y	R/W	00: 60°C 01: 80°C	Thermal regulation threshold. This bit is set to
2	T <sub>J_REG</sub> [0]	1	Y	Y	R/W	10: 100°C 11: 120°C	11 by default.
1	NTC OPT	0	Y	Y	R/W	0: Battery over- temperature protection (OTP) 1: PCB OTP	NTC OTP selection bit. This bit is set to 0 by default.
0	AICO_EN	0	Y	Ν	R/W	0: Disable AICO 1: Enable AICO	Automatic input current optimization enable bit. This bit is set to 0 by default.

#### **REG03H: ADC Control and OTG Configuration**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	ADC_START	0	Y	Y	R/W	0: Disable ADC 1: Enable ADC	ADC enable bit. Set to 0 by default. This bit is read-only when ADC_RATE = 1. This bit stays high during ADC conversion.
6	ADC_RATE	0	Y	Y	R/W	0: One-shot conversion 1: Start continuous conversion	This bit sets the ADC conversion rate. This bit is set to 0 by default.
5	VIN_DSCHG [2]	0	Y	Y	R/W	400mV	This bit sets the OTG
4	VIN_DSCHG [1]	1	Y	Y	R/W	200mV	voltage. The offset is 4.8V, the default is 5.0V (010), and
3	VIN_DSCHG [0]	0	Y	Y	R/W	100mV	the range is 4.8V to 5.5V.
2	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
1	IIN_DSCHG [1]	0	Y	Y	R/W	00: 0.5A 01: 0.8A	This bit sets the OTG current
0	I <sub>IN_DSCHG</sub> [0]	0	Y	Y	R/W	10: 1.1A 11: 1.5A	limit. It is set to 00 by default.

## **REG04H: Charge Control and VSYS Configuration**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	BAT_LOAD_EN	0	Y	Y	R/W	0: Disable IBATLOAD 1: Enable IBATLOAD	Battery load enable bit. It is set to 0 by default.
6	STAT_EN	1	Y	Y	R/W	0: Disable 1: Enable	STAT pin enable bit. It is set to 1 by default.
5	CHG_CONFIG [1]	0	Y	Y	R/W	00: Charge disabled	Charge configuration bit. It is
4	CHG_CONFIG [0]	1	Y	Y	R/W	01: Charge enabled 10: Reserved 11: OTG	set to 01 by default.
3	Vsys_min [2]	1	Y	Ν	R/W	000: 3V 001: 3.15V	This bit sets the minimum system voltage. It has a 3V offset, 3V to 3.75V range, and is set to 101 by default.
2	Vsys_min [1]	0	Y	Ν	R/W	010: 3.3V 011: 3.45V 100: 3.525V	
1	V <sub>SYS_MIN</sub> [0]	1	Y	Ν	R/W	101: 3.6V 110: 3.675V 111: 3.75V	
0	V <sub>TRACK</sub> [0]	1	Y	Ν	R/W	0: 100mV 1: 150mV	Battery track voltage bit. It is set to 150mV by default.

### **REG05H: Charge Current Configuration**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	Vbatt_pre	1	Y	Y	R/W	0: 2.8V 1: 3.0V	This bit sets the pre-charge to fast charge threshold. It is set to 1 by default.
6	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
5	I <sub>CC</sub> [5]	1	Y	Y	R/W	1344mA	
4	Icc [4]	0	Y	Y	R/W	672mA	This bit sets the fast charge
3	Icc [3]	0	Y	Y	R/W	336mA	current. It has a 320mA
2	I <sub>CC</sub> [2]	1	Y	Y	R/W	168mA	offset, 320mA to 2966mA range, and is set to 100110 by default.
1	lcc [1]	1	Y	Y	R/W	84mA	
0	Icc [0]	0	Y	Y	R/W	42mA	

## **REG06H: Pre-Charge and Termination Current**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	Ipre [3]	0	Y	Y	R/W	320mA	This bit set the pre-charge
6	I <sub>PRE</sub> [2]	0	Y	Y	R/W	160mA	current. It has a 150mA
5	I <sub>PRE</sub> [1]	1	Y	Y	R/W	80mA	offset, 150mA to 750mA range, and is set to 0010 by
4	Ipre [0]	0	Y	Y	R/W	40mA	default.
3	I <sub>TERM</sub> [3]	0	Y	Y	R/W	320mA	This hit acts the termination
2	Iterm [2]	0	Y	Y	R/W	160mA	This bit sets the termination current. It has a 120mA offset, 120 to 720mA range, and is set to 0010 by default.
1	Iterm [1]	1	Y	Y	R/W	80mA	
0	I <sub>term</sub> [0]	0	Y	Y	R/W	40mA	

#### **REG07H: Charge Voltage Regulation**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	Vbatt_reg <b>[5]</b>	1	Y	Y	R/W	640mV	
6	VBATT_REG [5]	0	Y	Y	R/W	320mV	
5	Vbatt_reg [4]	1	Y	Y	R/W	160mV	This bit sets the battery regulation voltage. It has a
4	Vbatt_reg [3]	0	Y	Y	R/W	80mV	3.4V offset, 3.4V to 4.67V range, and is set to 1010000 by default.
3	V <sub>BATT_REG</sub> [2]	0	Y	Y	R/W	40mV	
2	Vbatt_reg [1]	0	Y	Y	R/W	20mV	
1	Vbatt_reg [0]	0	Y	Y	R/W	10mV	
0	Vrech	0	Y	Y	R/W	0: 100mV 1: 200mV	This bit sets the battery recharge threshold (below $V_{BATT\_REG}$ ). It is set to 0 by default.

### **REG08H: Timer Configuration**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	EN_TERM	1	Y	Y	R/W	0: Disable 1: Enable	Termination enable bit. It is set to 1 by default.
6	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
5	WATCHDOG [1]	0	Y	Ν	R/W	00: Disable timer	The bit sets the I <sup>2</sup> C watchdog timer limit. It is set
4	WATCHDOG [0]	1	Y	Ζ	R/W	01: 40s 10: 80s 11: 160s	to 01 by default. The watchdog function is only available when a battery is present.
3	WATCHDOG TIMER RESET	0	Υ	Y	R/W	0: Normal 1: Reset	This bit is set to 0 by default, and returns to 0 after the timer resets.
2	CHG_TMR [1]	1	Y	Y	R/W	00: 5hrs	Constant current charge
1	CHG_TMR [2]	0	Y	Y	R/W	01: 8hrs 10: 12hrs 11: 20hrs	timer. This bit is set to 10 by default via the OTP.
0	EN_TIMER	1	Y	Y	R/W	0: Disable 1: Enable	Safety timer enable bit. This bit is set to 1 by default.

#### REG09H: Bandgap

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
6	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
5	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
4	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
3	BG_EN	0	Y	Y	R/W	0: Enable 1: Disable	This bit is set to 0 by default. Setting this bit from 1 to 0 resets the input plug-in detection and safety timer.
2	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
1	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
0	RESERVED	N/A	N/A	N/A	N/A	Reserved.	



## **REG0AH: BATFET Configuration**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	SW FREQ	0	Y	Y	R/W	0: 1.35MHz 1: 1MHz	This bit sets the switching frequency. It is set to 0 by default.
6	TMR2X_EN	1	Y	Y	R/W	0: Disable 2x extended safety timer 1: Enable 2x extended safety timer	2x timer enable bit. This bit is set to 1 by default.
5	BATFET_DIS	0	Ν	N	R/W	0: Allow BATFET to turn on 1: Force BATFET off	This bit is set to 0 by default.
4	SYSRST_SEL	1	Y	Ν	R/W	0: Hardware reset 1: Software reset	System reset selection bit. If this bit is set to 0, the DISC pin is pulled low for a time. Bit[1:0] turns off BATFET for a time until bit[3:2] turns on the BATFET. If this bit is set to 0, the off time is dependent on bit[3:2]. This bit is set to 1 by default.
3	t <sub>DISC_</sub> н [1]	1	Y	Y	R/W	00: 0.5s 01: 2s 10: 4s 11: 8s	DISC pin pull low time or BATFET off time to reset BATFET. This bit is 10 by default.
2	t <sub>DISC_H</sub> [0]	0	Y	Y	R/W		
1	toisc_L [1]	0	Y	Y	R/W	00: 8s 01: 10s 10: 12s 11: 16s	DISC pin pull low lasting time to turn off BATFET. This bit is 00 by default.
0	t <sub>DISC_L</sub> [0]	0	Y	Y	R/W		



#### **REG0BH: INT Mask and USB Detection**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	INT_MASK [1]	1	Y	Y	R/W	0: No INT during thermal shutdown (TSD) and safety timer fault 1: INT during TSD and safety timer fault	This bit it set to 1 by default.
6	INT_MASK [0]	1	Y	Y	R/W	0: No INT signal during BAT_FAULT 1: INT signal during BAT_FAULT	This bit is set to 1 by default.
5	USB_DET_EN	0	Y	Y	R/W	0: Not in DP/DM detection 1: Forced DP/DM detection	USB DP/DM detection enable bit. This bit is set to 0 by default.
4	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
3	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
2	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
1	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
0	RESERVED	N/A	N/A	N/A	N/A	Reserved.	


### **REG0CH: Status**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	VIN_STAT [2]	0	Ν	N	R	D+/D- version	
6	VIN_STAT [1]	0	Ν	N	R	000: No input 001: Nonstandard adapter	This bit selects the input
5	VIN_STAT [0]	0	Ν	Ν	R	(1A/2.1A/2.4A) 010: SDP 011: CDP 100/101: DCP 111: OTG	source. It is set to 000 by default. V <sub>IN</sub> POR resets VIN_STAT.
4	CHG_STAT [1]	0	Ν	N	R	00: Not charging 01: Trickle charge	
3	CHG_STAT [0]	0	N	N	R	10: Constant current charge 11: Charging complete	This bit is set to 00 by default.
2	RNTC FLOAT_STAT	0	Ν	Ν	R	0: No NTC float 1: NTC float	This bit is set to 0 by default.
1	THERM_ STAT	0	Ν	N	R	0: Normal 1: Thermal regulation	This bit is set to 0 by default.
0	VSYS_STAT	1	Ν	N	R	0: In VSYSMIN regulation (BAT < V <sub>SYSMIN</sub> ) 1: Not in VSYSMIN regulation (BAT > V <sub>SYSMIN</sub> )	This bit is set to 1 by default.



### **REG0DH: Fault**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	WATCHDOG_ FAULT	0	Z	Ν	R	0: Normal 1: Watchdog timer expiration	This bit is set to 0 by default.
6	OTG_FAULT	0	Ζ	Ν	R	0: Normal 1: V <sub>IN</sub> overloaded, or V <sub>IN</sub> over-voltage protection (OVP), or battery is under- voltage	This bit is set to 0 by default.
5	INPUT_FAULT	0	Ν	N	R	0: Normal 1: Input over- voltage protection (OVP) or no input	This bit is set to 0 by default.
4	THERMAL SHUTDOWN	0	Ν	Ν	R	0: Normal 1: Thermal shutdown	This bit is set to 0 by default.
3	BAT_FAULT	0	Ν	Ν	R	0: Normal 1: Battery over- voltage protection (OVP)	This bit is set to 0 by default.
2	NTC_FAULT [2]	0	Ν	N	R	Buck mode 000: Normal	
1	NTC_FAULT [1]	0	Ν	N	R	010: NTC warm	
						011: NTC cool 101: NTC cold 110: NTC hot	This bit is set to 000 by default.
0	NTC_FAULT [0]	0	Ν	Ν	R	Boost mode 000: Normal 101: NTC cold 110: NTC hot	

#### **REG0EH: ADC of Battery Voltage**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	VBATT [7]	0	Ν	N	R	2560mV	
6	VBATT [6]	0	N	N	R	1280mV	
5	VBATT [5]	0	N	N	R	640mV	
4	VBATT [4]	0	N	Ν	R	320mV	This bit selects the ADC conversion of the battery cell
3	VBATT [3]	0	N	Ν	R	160mV	voltage. It has a 0V offset, and a 0V to 5.1V range.
2	VBATT [2]	0	N	Ν	R	80mV	and a 0V to 5.1V lange.
1	VBATT [1]	0	N	Ν	R	40mV	
0	VBATT [0]	0	Ν	Ν	R	20mV	

### **REG0FH: ADC of System Voltage**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	VSYS [7]	0	Ν	Ν	R	2560mV	
6	VSYS [6]	0	Ν	Ν	R	1280mV	
5	VSYS [5]	0	Ν	Ν	R	640mV	
4	VSYS [4]	0	Ν	N	R	320mV	This bit sets the ADC conversion of the system
3	VSYS [3]	0	Ν	Ν	R	160mV	voltage. It has a 0V offset and 0V to 5.1V range.
2	VSYS [2]	0	Ν	N	R	80mV	and 0v to 5.1 v range.
1	VSYS [1]	0	Ν	N	R	40mV	
0	VSYS [0]	0	Ν	Ν	R	20mV	

#### **REG10H: ADC of NTC Voltage**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	NTC [7]	0	Ν	Ν	R	50.176%	
6	NTC [6]	0	Ν	Ν	R	25.088%	
5	NTC [5]	0	Ν	Ν	R	12.544%	
4	NTC [4]	0	N	N	R	6.272%	This bit sets the ADC conversion of the NTC
3	NTC [3]	0	Ν	Ν	R	3.136%	voltage. It has a 0% offset and 0% to 100% range.
2	NTC [2]	0	N	N	R	1.568%	and 0% to 100% fange.
1	NTC [1]	0	N	N	R	0.784%	
0	NTC [0]	0	Ν	Ν	R	0.392%	

#### **REG11H: ADC of Input Voltage**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
6	VIN [6]	0	N	N	R	3840mV	
5	VIN [5]	0	Ν	Ν	R	1920mV	
4	VIN [4]	0	N	Ν	R	960mV	This bit sets the ADC
3	VIN [3]	0	N	N	R	480mV	conversion of the input voltage. It has a 0V offset
2	VIN [2]	0	N	N	R	240mV	and a 3.6V to 7.62V range.
1	VIN [1]	0	N	Ν	R	120mV	
0	VIN [0]	0	Ν	Ν	R	60mV	

### **REG12H: ADC of Charge Current**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	Існд [7]	0	Ν	Ν	R	2240mA	
6	I <sub>СНG</sub> [6]	0	Ν	Ν	R	1120mA	
5	Існд [5]	0	Ν	Ν	R	560mA	The bit este the ADO
4	Існд [4]	0	Ν	N	R	280mA	The bit sets the ADC conversion of the charge
3	I <sub>СНG</sub> [3]	0	Ν	Ν	R	140mA	current. It has a 0A offset and a 0A to 5.66A range.
2	Існд [2]	0	Ν	N	R	70mA	and a OA to 5.00A range.
1	Існд [1]	0	Ν	N	R	35mA	
0	I <sub>СНG</sub> [0]	0	Ν	Ν	R	17.5mA	

#### **REG13H: ADC of Input Current**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	I <sub>IN</sub> [7]	0	Ν	Ν	R	1702.4mA	
6	I <sub>IN</sub> [6]	0	Ν	Ν	R	851.2mA	
5	IIN [5]	0	Ν	Ν	R	425.6mA	This hit sats the ADO
4	I <sub>IN</sub> [4]	0	Ν	Ν	R	212.8mA	This bit sets the ADC conversion of the input
3	I <sub>IN</sub> [3]	0	Ν	Ν	R	106.4mA	current. It has a 0A offset and a 0A to 3.39A range.
2	I <sub>IN</sub> [2]	0	Ν	Ν	R	53.2mA	a OA to 5.55A lange.
1	I <sub>IN</sub> [1]	0	Ν	Ν	R	26.6mA	
0	I <sub>IN</sub> [0]	0	Ν	Ν	R	13.3mA	

#### **REG14H: Power Management Status**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	VINPPM_STAT	0	Ν	N	R	0: No PPM 1: VINPPM	This bit is set to 0 by default.
6	IINPPM_STAT	0	N	N	R	0: No PPM 1: IINPPM	This bit is set to 0 by default.
5	IIN_DPM [5]	0	N	N	R	1600mA	
4	IIN_DPM [4]	0	N	N	R	800mA	
3	I <sub>IN_DPM</sub> [3]	1	Ν	Ν	R	400mA	This bit has a 100mA offset, a 100mA to 3.25A range, and is
2	IIN_DPM [2]	0	N	N	R	200mA	001000 by default.
1	IIN_DPM [1]	0	Ν	Ν	R	100mA	
0	IIN_DPM [0]	0	N	N	R	50mA	



#### REG15H: DPM Mask

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	AICO_STAT	0	Z	Ν	R	0: No operation 1: AICO action	This bit indicates the AICO status. It is set to 0 by default.
6	VINPPM_INT_ MASK [1]	1	Y	Y	R/W	0: No INT during VINPPM 1: INT in VINPPM	This bit is 1 by default.
5	IINPPM_INT_ MASK [1]	1	Y	Y	R/W	0: No INT during IINPPM 1: INT in IINPPM	This bit is 1 by default.
4	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
3	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
2	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
1	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
0	RESERVED	N/A	N/A	N/A	N/A	Reserved.	

## **REG16H: JEITA Configuration**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	JEITA_VSET	1	Y	Y	R/W	0: V <sub>BATT_REG</sub> minus 100mV 1: V <sub>BATT_REG</sub> minus 200mV	This bit is set to 1 by default.
6	JEITA_ISET	1	Y	Y	R/W	0: 50% of ICHG 1: 16.7% of ICHG	This bit is set to 1 by default.
5	Vнот	1	Y	Y	R/W	0: 34.0% (60°C) 1: 36.0% (55°C)	This bit sets the hot threshold. It is set to 1 by default. The thermistor is 103AT.
4	Vwarm [1]	0	Y	Y	R/W	00: 43.0% (40°C) 01: 40.0% (45°C) 40: 22.0% (50°C)	This bit sets the warm threshold. It is set to 01 by
3	Vwarm [0]	1	Y	Y	R/W	10: 38.0% (50°C) 11: 36.0% (55°C)	default. The thermistor is 103AT.
2	Vcool [1]	1	Y	Y	R/W	00: 72.0% (0°C) 01: 68.0% (5°C)	This bit sets the cool threshold. It is set to 11 by
1	V <sub>COOL</sub> [0]	1	Y	Y	R/W	10: 64.0% (10°C) 11: 60.0% (15°C)	default. The thermistor is 103AT.
0	Vcold	0	Y	Y	R/W	0: 72.0% (0°C) 1: 68.0% (5°C)	This bit sets the cold threshold. It is set to 0 by default. The thermistor is 103AT.

### **REG17H: Safety Timer Status and Part Number**

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	SAFETY TIMER	0	Ν	Ν	R	0: Normal 1: Safety timer expiration	This bit is set to 0 by default.
6	RESERVED	N/A	N/A	N/A	N/A		
5	PN [2]	0	Ν	N	R		
4	PN [1]	0	Ν	N	R	000: MP2723	This bit is set to 000 by default.
3	PN [0]	0	Ν	Ν	R		
2	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
1	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
0	RESERVED	N/A	N/A	N/A	N/A	Reserved.	

#### **REG18H**<sup>(7)</sup>

Bit	Name	POR	Reset by REG_RST	Reset by WTD	R/W	Description	Comment
7	IINLIM/VINMIN RESET_EN	0	Z	Ζ	Ν	0: IIN_LIM and VIN_MIN are not reset when V <sub>IN</sub> POR 1: IIN_LIM and VIN_MIN reset when V <sub>IN</sub> POR	This bit is set to 0 by default.
6	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
5	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
4	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
3	RESERVED	N/A	N/A	N/A	N/A	Reserved.	
2	ADDRESS	0	N/A	N/A	N/A	0: 4BH 1: 21H	This bit is set to 0 by default.
1	PFM_EN	0	N/A	N/A	N/A	0: Enable 1: Disable	This bit enables or disables PFM when charging is disabled. It is set to 0 by default.
0	RESERVED	N/A	N/A	N/A	N/A	Reserved.	

#### Note:

7) This register is one-time programmable (OTP). It is not accessible.



## **OTP MAP**

#	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
00	N/A lin				/ (100mA to 3250mA/50mA step)				
01	N/A VIN_MIN (3.7V to 5.2V/100mV s					V/100mV ste	p)		
05	N/A Icc (320mA to 2966mA/42mA					mA/42mA ster	эр)		
07	VBATT_REG (3.4V to 4.67V/10mV step)						N/A		
08	N/A CHG_TMR					TMR	N/A		
18	IINLIM/ VINMIN RESET_EN	N/A	N/A	N/A	N/A	ADDRESS	PFM_EN	N/A	

### **OTP DEFAULT**

OTP Settings	Default
lin_lim	500mA
Vin_min	4.3V
lcc	1.92A
Vbatt_reg	4.2V
CHG_TMR	12hrs
INLIM/VINMIN RESET_EN	IIN_LIM and VIN_MIN do not reset when VIN POR
ADDRESS	4BH
PFM_EN	Enable

## **APPLICATION INFORMATION**

#### Setting the Input Current Limit

The input current limit is set according to the input power source. The input current limit can be set through the I<sup>2</sup>C using the MP2723's GUI. If a user wants to set a current limit that cannot be set by the I<sup>2</sup>C, it can be set using the ILIM pin. Connect a resistor from the ILIM pin to AGND to program the input current limit. The MP2723 selects the lower limit between the I<sup>2</sup>C setting and the resistor setting. The resistor for the ILIM pin resistor can be determined with Equation (1) on page 22.

See Table 2 on page 23 to determine how to set the input current limit for USB inputs.

#### Selecting the Inductor

Inductor selection is a tradeoff between cost, size, and efficiency. A smaller-value inductor is physically small, but results in higher ripple current, magnetic hysteretic loss, and output capacitance. A larger-value inductance provides lower ripple current and smaller output filter capacitors, but results in higher inductor DC resistance (DCR) loss.

For the best results, the inductor ripple current should not exceed 30% of the maximum load current under the worst-case conditions. For the MP2723 to operate with a typical 5V input voltage, the maximum inductor current ripple occurs at the corner point between pre-charge and CC charge. The inductance (L) can be estimated with Equation (2):

$$L = \frac{V_{IN} - V_{SYS}}{\Delta I_{L_{MAX}}} \frac{V_{SYS}}{V_{IN} \times f_{SW}(MHz)} (\mu H)$$
(2)

Where V<sub>IN</sub> is the input voltage, V<sub>SYS</sub> is the system voltage, fsw is the switching frequency, and  $\Delta I_{L_MAX}$  is the maximum inductor ripple current, which is usually 30% of the CC charge current. I<sub>PEAK</sub> can be calculated with Equation (3):

$$I_{\text{PEAK}} = I_{\text{LOAD(MAX)}} \times (1 + \frac{\% \text{ripple}}{2})(A)$$
 (3)

The maximum charge current can be set to 3A, but the real charge current cannot reach the input current limit. To cover most typical applications and to give enough margin to avoid hit the peak current limit of the high-side switch, the maximum inductor current ripple is set to 0.5A with  $5V_{IN}$ , and the inductance is  $1.5\mu$ H. Select  $1.0\mu$ H for lowprofile operation. To optimize efficiency, chose an inductor with a low DC resistance.

#### **Selecting the Input Capacitor**

The step-down converter has a discontinuous input current, and requires a capacitor to supply the AC current to the converter while maintaining the DC input voltage. Use low-ESR capacitors for the best performance. Ceramic capacitors are recommended, but tantalum or low-ESR electrolytic capacitors are sufficient. Choose ceramic capacitors with X5R or X7R dielectrics.

Since the input capacitor  $(C_{IN})$  absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in the input capacitor can be estimated with Equation (4):

$$I_{CIN} = I_{LOAD} \times \sqrt{\frac{V_{SYS}}{V_{IN}}} \left(1 - \frac{V_{SYS}}{V_{IN}}\right)$$
(4)

The worst-case condition occurs when  $V_{IN} = 2V_{SYS}$ , and  $I_{CIN} = I_{SYS} / 2$ . For simplification, choose the input capacitor whose RMS current rating exceeds half of the maximum load current.

For the MP2723, the RMS current in the input capacitor is from PMID to GND. This means a small, high-quality ceramic capacitor (e.g.  $10\mu$ F) should be placed from VPMID to PGND, as close to the IC as possible. The remaining capacitor should be from VIN to GND.

With ceramic capacitors, ensure that they have enough capacitance to provide a sufficient charge that prevents excessive voltage ripple at the input.

#### Selecting the Output Capacitor

In the typical application circuit, the output capacitor ( $C_{SYS}$ ) is in parallel with the SYS load.  $C_{SYS}$  absorbs the high-frequency switching ripple current and smooths the output voltage. Its impedance must be below that of the system load to ensure that it properly absorbs the ripple current.

Use a ceramic capacitor since its low ESR and small size allows the output capacitor's ESR to be ignored.

The output voltage ripple can be calculated with Equation (5):

$$\Delta R = \frac{\Delta V_{SYS}}{V_{SYS}} = \frac{1 - \frac{V_{SYS}}{V_{IN}}}{8 \times C_{SYS} \times f_{SW}^2 \times L}\%$$
(5)

To guarantee the  $\pm 0.5\%$  system voltage accuracy, the maximum output voltage ripple must not exceed 0.5% (e.g. 0.1%). The maximum output voltage ripple occurs at the minimum system voltage and the maximum input voltage.

The output capacitor can be calculated with Equation (6):

$$C_{SYS} = \frac{1 - \frac{V_{SYS}}{V_{IN}}}{8 \times f_{SW}^{2} \times L \times \Delta R}$$
(6)

For example, if  $V_{IN} = 5V$ ,  $V_{SYS} = 3.7V$ ,  $L = 1\mu H$ ,  $f_{SW}$ = 1.35MHz, and  $\Delta R$  = 0.1%, choose a 22µF ceramic capacitor.

#### Selecting the NTC Resistor

Figure 6 on page 22 shows an external resistor divider reference circuit that limits the hightemperature threshold (V<sub>HOT</sub>) and low-temperature threshold (V<sub>COLD</sub>). For a given NTC thermistor, select the appropriate  $R_{T2}$  and  $R_{T1}$  to set the NTC window, calculated with Equation (7) and Equation (8), respectively:

$$R_{T2} = \frac{R_{NTC\_HOT} \times V_{COLD} \times (1 - V_{HOT}) - R_{NTC\_COLD} \times V_{HOT} \times (1 - V_{COLD})}{V_{HOT} - V_{COLD}} \dots (7)$$

$$R_{T1} = \frac{(1 - V_{COLD}) \times (R_{NTC\_COLD} + R_{T2})}{V_{COLD}} (8)$$

R<sub>NTC HOT</sub> is the value of the NTC resistor at the high temperature of the required temperature operation range, and R<sub>NTC COLD</sub> is the value of the NTC resistor at the low temperature.

 $R_{T1}$  and  $R_{T2}$  allow the high-temperature limit and low-temperature limit be configured to independently. With this feature, the MP2723 can operate with most NTC and temperature operation range requirements.

The  $R_{T1}$  and  $R_{T2}$  values depend on the type of the NTC resistor. For example, for the 103AT thermistor, it has the following electrical characteristics:

- At 0°C, RNTC COLD =  $27.28k\Omega$
- At 60°C,  $R_{NTC_HOT} = 3.02 k\Omega$

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 $V_{HOT}$  is selected at 34%, and  $V_{COLD}$  is selected at 72% via the REG16H register. Using Equation (7) and Equation (8),  $R_{T1} = 11.8k\Omega$  and  $R_{T2} = 3.06k\Omega$ .

#### PCB Layout Guidelines

Careful PCB layout is critical to meet specified noise rejection requirements and efficiency. For the best results, follow the guidelines below:

- 1. Route the power stage adjacent to their grounds. Minimize the high-side switching node (SW and inductor), the trace lengths in the high-current paths, and the current-sense resistor trace.
- 2. Keep the switching node short and route it away from all small control signals, especially the feedback network.
- 3. Place the input capacitor as close as possible to the PMID and PGND pins.
- 4. Place the output inductor close to the IC, and connect the output capacitor between the inductor and PGND of the IC.
- 5. For high-current applications, the pins for the power pads (IN, SW, SYS, BATT, and PGND) should be connected to as much copper in the board as possible. This improves thermal performance by conducting heat away from the IC.
- 6. Connect a ground plane directly to the return of all components through via holes. It is also recommended to put via holes inside the PGND pads for the IC, if possible. A star ground design approach is typically used to keep circuit block currents isolated (highpower/low-power small signal) which reduces noise-coupling and ground-bounce issues. A single ground plane for this design gives good results. With this small layout and a single ground plane, there is no ground-bounce issue, and having the components separated minimizes coupling between signals and stability requirements.
- 7. Pull the connection wire from the MCU (I<sup>2</sup>C) far from the SW mode and cooper regions. SCL and SDA should be in close parallel.



## **TYPICAL APPLICATION CIRCUIT**



Figure 18: MP2723 Typical Application Circuit

04.4								
Qty	Ref	Value	Description	Package	Manufacturer			
1	C1	1µF	Ceramic capacitor, 50V, X5R or X7R	0603	Any			
1	C2	10µF	Ceramic capacitor, 50V, X5R or X7R	0603	Any			
1	C3	10µF	Ceramic capacitor, 16V, X5R or X7R	0603	Any			
1	C4	47nF	Ceramic capacitor, 16V, X5R or X7R	0603	Any			
1	C5	22µF	Ceramic capacitor, 16V, X5R or X7R	0805	Any			
1	C6	22µF	Ceramic capacitor, 16V, X5R or X7R	0805	Any			
1	L1	1.0µH	>9.6A		Any			

Table 3: Key BOM for	or Typical Application	Circuit
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## PACKAGE INFORMATION

QFN-26 (3.5mmx3.5mm)



TOP VIEW



**BOTTOM VIEW** 





#### NOTE:

 ALL DIMENSIONS ARE IN MILLIMETERS.
 LEAD COPLANARITY SHALL BE 0.08 MILLIMETERS MAX.
 JEDEC REFERENCE IS MO-220.
 DRAWING IS NOT TO SCALE.



## **CARRIER INFORMATION**



Part Number	Package Description	Quantity/ Reel	Quantity/ Tube	Quantity/ Tray	Reel Diameter	Carrier Tape Width	Carrier Tape Pitch	Trailer Leader/Reel
MP2723GQC- xxxx–Z	QFN-26 (3.5mmx 3.5mm)	5000	N/A	N/A	13in	12mm	8mm	125&125



## **Revision History**

Revision #	Revision Date	Description	Pages Updated
1.0	05/27/2020	Initial Release	-
	08/21/2020	1. Update Features section	Page 1
1.1		2. Update safety timer expiration reset actions	Page 24
1.1		3. Add function description for BG_EN bit	Page 34
		4. Update Table 3	Page 46

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